

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT(S):

Fitzgerald

CONFIRMATION NO.:

8754

SERIAL NO.:

10/774,890

GROUP NO.:

2818

FILING DATE:

February 9, 2004

EXAMINER:

Tran, Mai Huong

TITLE:

RELAXED SiGe PLATFORM FOR HIGH SPEED CMOS

ELECTRONICS AND HIGH SPEED ANALOG CIRCUITS

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

In accordance with the provisions of 37 C.F.R. 1.97 and 1.98, Applicants hereby make of record the patents and publications listed on the accompanying Form PTO-1449, and other information contained herein, for consideration by the Examiner in connection with the examination of the above-identified patent application. Copies of the patents and publications are enclosed. In accordance with the U.S. Patent Office's partial waiver of the requirement under 37 C.F.R. 1.98 (a)(2)(i), only copies of the foreign patent documents and non-patent publications are enclosed.

REMARKS

In a	accordar	nce with the provisions of 37 C.F.R. 1.97, this statement is being filed (CHECK
ONE):		
	(1)	within three (3) months of the filing date of a national application other than a continued prosecution application under 37 C.F.R. 1.53(d), or within three (3) months of the date of entry of the national stage as set forth in 37 C.F.R. 1.491 in an international application, or before the mailing of the first Office action on the merits, or before the mailing of a first Office action after the filing of a request for continued examination under 37 C.F.R. 1.114; or
\boxtimes	(2)	after the period defined in (1) but before the mailing date of a final action or a

notice of allowance under 37 C.F.R. 1.311, and

the requisite Statement is below, OR

Information Disclosure Statement Serial No. 10/774,890 Page 2 of 3

\boxtimes	the requisite fee under 37 C.F.R. 1.17(p), namely \$180.00, is included herein, or
(3)	after the mailing date of a final action or notice of allowance but before the payment of the issue fee, AND
	the requisite Statement is below, AND
	the requisite petition fee under 37 C.F.R. 1.17(p), namely \$180.00 is included herein.

Applicant wishes to inform the Examiner about the following co-pending patent applications and Office actions issued therein:

- 1) U.S. Serial No. 09/611,024 (Docket No. ASC-023) filed on 06/07/2000, by Fitzgerald;
- 2) U.S. Serial No. 10/611,739 (Docket No. ASC-044C1) filed on 07/01/2003, by Fitzgerald et al.;
- 3) U.S. Serial No. 10/802,185 (Docket No. ASC-025DVC1) filed on 03/17/2004, by Cheng et al.;
- 4) U.S. Serial No. 10/802,186 (Docket No. ASC-025DV2C1) filed on 03/17/2004, by Cheng et al.;
- 5) U.S. Serial No. 10/826,156 (Docket No. ASC-023C2) filed on 04/16/2004, by Fitzgerald;
- 6) U.S. Serial No. 10/854,556 (Docket No. ASC-054C1), filed May 26, 2004, by Fitzgerald;
- 7) U.S. Serial No. 09/884,817 (Docket No. ASC-043), filed June 19, 2001 by Fitzgerald et al.;
- 8) U.S. Serial No. 10/022,689 (Docket No. ASC-023DVC2), filed December 17, 2001 by Fitzgerald;
- 9) U.S. Serial No. 09/906,534 (Docket No. ASC-054), filed July 16, 2001 by Fitzgerlad;
- 10) U.S. Serial No. 09/906,533 (Docket No. ASC-052), filed July 16, 2001 by Fitzgerald;
- 11) U.S. Serial No. 10/005,274 (Docket No. ASC-043CP), filed December 4, 2001 by Fitzgerald et al.;
- 12) U.S. Serial No. 10/116,559 (Docket No. ASC-026), filed April 4, 2002 by Cheng et al.;
- 13) U.S. Serial No. 10/172,542 (Docket No. ASC-057), filed June 14, 2002 by Hammond et al.;
- 14) U.S. Serial No. 10/266,399 (Docket No. ASC-043C1), filed October 8, 2002 by Fitzgerald et al.;
- 15) U.S. Serial No. 10/253,361 (Docket No. ASC-018), filed September 24, 2002 by Braithwaite et al.;
- 16) U.S. Serial No. 10/389,003 (Docket No. ASC-019), filed March 14, 2003 by Fitzgerald et al.;
- 17) U.S. Serial No. 10/264,935 (Docket No. ASC-008), filed October 4, 2002 by Lochtefeld et al.;
- 18) U.S. Serial No. 10/456,103 (Docket No. ASC ASC-008C), filed June 6, 2003 by Lochtefeld et al.;
- 19) U.S. Serial No. 10/456,708 (Docket No. ASC ASC-008B), filed June 6, 2003 by Lochtefeld; and
- 20) U.S. Serial No. 10/625,018 (Docket No. ASC-043C2), filed by Fitzgerald et al.

Information Disclosure Statement Serial No. 10/774,890 Page 3 of 3

It is respectfully requested that the patents and publications listed on the attached Form PTO-1449, and other information contained herein, be made of record in this application.

Respectfully submitted,

Date: <u>Sept-8, 2004</u> Reg. No. 44,381

Tel. No.: (617) 248-7453 Fax No.: (617) 248-7100

3081965

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INFORMATION DISCLOSURE STATEMENT



ATTY DOCKET NO.: ASC-049C1

APPLICANT: Fitzgerald

SERIAL NO.: 10/774,890

FILING DATE: February 9, 2004

EXAMINER: Tran, Mai Huong C.

GROUP: 2818

EXAM. INIT.	DOCUMENT NUMBER		DATE NAME			CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	A1	2001/0003364	06/14/2001	Sugawara	et al.			
	A2	2002/0024395	02/28/2002	Akatsuka e	et al.			
	A3	2002/0043660	04/18/2002	Yamazaki et al.				
	A4	2002/0084000	07/04/2002	Fitzgerald				
	A5	2002/0096717	07/25/2002	Chu et al.				
<u> </u>	A6	2002/0100942	08/01/2002	Fitzgerald et al.				
	A7	2002/0123167	09/05/2002	Fitzgerald				,
	A8	2002/0123183	09/05/2002	Fitzgerald				
	A9	2002/0125471	09/12/2002	Fitzgerald	et al.			
	A10	2002/0168864	11/14/2002	Cheng et al.				
	A11 2003/0003679		01/02/2003	Doyle et al	!.			
	A12	2003/0013323	01/16/2003	Hammond et al.				
	A13	2003/0034529	02/20/2003	Fitzgerald	et al.			
	A14	2003/0057439	03/27/2003	Fitzgerald				
	A15	2003/0102498	06/05/2003	Braithwait	e et al.			
	A16	2003/0199126	10/23/2003	Chu et al.				
	A17	2003/0203600	10/30/2003	Chu et al.				
	A18	2003/0215990	11/20/2003	Fitzgerald	et al.			
	A19	2003/0218189	11/27/2003	Christianse	en			
	A20	2003/0227057	12/01/2003	Lochtefeld	et al.			
	A21	2004/0005740	01/01/2004	Lochtefeld	et al.			
	A22	2004/0014304	01/22/2004	Bhattachar	ууа			
	A23	2004/0031979	02/19/2004	Lochtefeld				06/06/2003
EXAM	INER		J		DATE CONS	SIDERED	<u> </u>	

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	A24	2004/0041210	03/04/2004	Mouli			09/02/2003
	A25	2004/0075149	04/22/2004	Fitzgerald et al.			07/23/2003
	A26	4,010,045	03/01/1977	Ruehrwein		#***	
	A27	4,710,788	12/01/1987	Dambkes et al.			-
	A28	4,987,462	01/22/1991	Kim et al.			
	A29	4,990,979	02/05/1991	Otto			
	A30	4,997,776	03/05/1991	Harame et al.			
	A31	5,013,681	05/07/1991	Godbey et al.			
-	A32	5,155,571	10/13/1992	Wang et al.			
	A33	5,166,084	11/24/1992	Pfiester			
	A34	5,177,583	01/05/1993	Endo <i>et al</i> .			
	A35	5,202,284	04/13/1993	Kamins et al.			
	A36	5,207,864	05/04/1993	Bhat et al.			
	A37	5,208,182	05/04/1993	Narayan et al.			
	A38	5,212,110	05/18/1993	Pfiester et al.			
	A39	5,221,413	06/22/1993	Brasen et al.			
	A40	5,240,876	08/34/1993	Gaul et al.			
	A41	5,241,197	08/31/1993	Murakami et al.			
 	A42	5,250,445	10/05/1993	Bean et al.			
······································	A43	5,285,086	02/08/1994	Fitzgerald			
	A44	5,291,439	03/01/1994	Kauffmann et al.			
	A45	5,298,452	03/29/1994	Meyerson			
	A46	5,310,451	05/10/1994	Tejwani <i>et al</i> .			

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	A47	5,316,958	05/31/1994	Meyerson			
	A48	5,346,848	09/13/1994	Grupen-Shemansky et al.			
-	A49	5,374,564	12/20/1994	Bruel			
	A50	5,399,522	03/21/1995	Ohori			
	A51	5,413,679	05/09/1995	Godbey			
	A52	5,424,243	06/13/1995	Takasaki			
	A53	5,426,069	06/20/1995	Selvakumar et al.			
	A54	5,426,316	06/20/1995	Mohammad			-
	A55	5,442,205	08/15/1995	Brasen et al.			!
	A56	5,461,243	10/24/1995	Ek et al.		 	
	A57	5,461,250	10/24/1995	Burghartz et al.			
	A58	5,462,883	10/31/1995	Dennard et al.			
	A59	5,476,813	12/19/1995	Naruse		 	
	A60	5,479,033	12/26/1995	Baca et al.			
	A61	5,484,664	01/16/1996	Kitahara et al.			
	A62	5,523,243	06/04/1996	Mohammad			
	A63	5,523,592	06/04/1996	Nakagawa et al.			
	A64	5,534,713	07/09/1996	Ismail et al.			
	A65	5,536,361	07/16/1996	Kondo et al.			
	A66	5,540,785	07/30/1996	Dennard et al.		 	
	A67	5,572,043	11/05/1996	Shimizu et al.	-		
	A68	5,596,527	01/21/1997	Tomioka et al.			
	A69	5,617,351	04/01/1997	Bertin et al.			

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	A70	5,630,905	05/20/1997	Lynch et al.			
	A71	5,659,187	08/19/1997	Legoues et al.			
	A72	5,683,934	11/04/1997	Candelaria			
	A73	5,698,869	12/16/1997	Yoshimi et al.			
	A74	5,714,777	02/03/1998	Ismail et al.			
	A75	5,728,623	03/17/1998	Mori			·
	A76	5,739,567	04/14/1998	Wong			
	A77	5,759,898	06/02/1998	Ek et al.			
	A78	5,777,347	07/07/1998	Bartelink			
	A79	5,786,612	07/28/1998	Otani et al.			1
	A80	5,786,614	07/28/1998	Chuang et al.			
	A81 5,792,679 08/1		08/11/1998	Nakato			
	A82	5,808,344	09/15/1998	Ismail et al.			
	A83	5,847,419	12/08/1998	Imai et al.			
	A84	5,877,070	03/02/1999	Goesele et al.			
	A85	5,891,769	04/06/1999	Liaw et al.			
	A86	5,906,708	05/25/1999	Robinson et al.			
 	A87	5,906,951	05/25/1999	Chu et al.			
	A88	5,912,479	06/15/1999	Mori et al.			
	A89	5,943,560	08/24/1999	Chang et al.			
	A90	5,963,817	10/05/1999	Chu et al.			
·	A91	5,966,622	10/12/1999	Levine et al.			
	A92	5,998,807	12/07/1999	Lustig et al.			

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ii	A93	6,013,134	01/11/2000	Chu et al.			
	A94	6,030,887	02/29/2000	Desai et al.			
	A95	6,030,889	02/29/2000	Aulicino et al.			
	A96	6,033,974	03/07/2000	Henley et al.			
	A97	6,033,995	03/07/2000	Muller			
	A98	6,058,044	05/02/2000	Sugiura et al.			
	A99	6,059,895	05/09/2000	Chu et al.			
	A100	6,074,919	06/13/2000	Gardner et al.			<u>.</u>
	A101	6,096,590	08/01/2000	Chan et al.			
	A102	6,103,559	08/15/2000	Gardner et al.			
	A103	6,107,653	08/22/2000	Fitzgerald			
	A104	6,111,267	08/29/2000	Fischer et al.			
	A105	6,117,750	09/12/2000	Bensahel et al.			
	A106	6,130,453	10/10/2000	Mei et al.			
	A107	6,133,799	10/17/2000	Favors et al.			
	A108	6,140,687	10/31/2000	Shimomura et al.			
	A109	6,143,636	11/07/2000	Forbes et al.			
	A110	6,153,495	11/28/2000	Kub et al.			
	A111	6,154,475	11/28/2000	Soref et al.			
	A112	6,160,303	12/12/2000	Fattaruso			
	A113	6,162,688	12/19/2000	Gardner et al.			
	A114	6,184,111	02/06/2001	Henley et al.			
	A115	6,191,007	02/20/2001	Matsui et al.			

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U.S. PATENT DOCUMENTS

NAME		E N	DOCUMENT NUMBER		EXAM. INIT.			
	Sugiyama et a	20/2001 8	02/20/2	32	6,191,432	6 6,191	A116	
Fiorini et al.		.7/2001 F	02/27/2	22	6,194,722	7 6,194	A117	, ,
	Lung et al.	.0/2001 I	03/20/2	29	6,204,529	8 6,204	A118	
	Augusto	7/2001	03/27/2	77	6,207,977	9 6,207	A119	
	Howe et al.	3/2001 I	04/03/2	88	6,210,988	0 6,210	A120	
	Broekaert	A121 6,218,677 04/17/2001 Br						
Fitzgerald et al.		5/2001 F	05/15/2	38	6,232,138	2 6,232	A122	
	Huang	2/2001 F	05/22/2	67	6,235,567	A123 6,235,567		
Kub et al. Lin et al.								
	Furukawa et a	26/2001 Furukav		55	6,251,755	6 6,251	A126	
	Gehrke et al.	7/2001	07/17/2	29	6,261,929	7 6,261	A127	
	Harari et al.	4/2001 F	07/24/2	78	6,266,278	8 6,266	A128	· · · · · · · · · · · · · · · · · · ·
	Schmitz et al.	7/2001 \$	08/07/2	51	6,271,551	9 6,271	A129	
	Fransis et al.	7/2001 F	08/07/2	26	6,271,726	0 6,271	A130	
	Fitzgerald	8/2001 F	09/18/2	21	6,291,321	1 6,291	A131	
	Kibbel et al.	6/2001 F	11/06/2	16	6,313,016	2 6,313	A132	
	Kant	3/2001 F	11/13/2	01	6,316,301	3 6,316	A133	
	Kub et al.	7/2001 F	11/27/2	08	6,323,108	4 6,323	A134	
	Lo et al.	1/2001 I	12/11/2	63	6,329,063	5 6,329	A135	
Tsuda et al.			A136 6,335,546 01/01/2002 Tsu					
	Takagi	5/2002 7	01/15/2	32	6,339,232	7 6,339	A137	
	Chu et al.	26/2002 (02/26/2	93	6,350,993	8 6,350	A138	
E CO	Chu et al.					8 6,350	A138	EXAMI

EXAMINER

DATE CONSIDERED

INFORMATION DISCLOSURE STATEMENT

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U.S. PATENT DOCUMENTS

EXAM. INIT.	DOCUMENT NUMBER		DATE	NAME		CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	A139	6,352,909	03/05/2002	Usenko				
	A140	6,368,733	. 04/09/2002	Nishinaga				
	A141	6,372,356	04/16/2002	Thornton 6	et al.			
	A142	6,372,593	04/16/2002	Hattori et	al.			
	A143	6,399,970	06/04/2002	Kubo et al	!.			
	A144	6,403,975	06/11/2002	Brunner et	t al.			
	A145	6,407,406	06/18/2002	Tezuka				
	A146	6,420,937	07/16/2002	Chu et al. Rim Wu et al.				
	A147	6,425,951	07/30/2002					
	A148	6,429,061	08/06/2002					
	A149	6,521,041	02/18/2003					1,000,00
	A150	6,524,935	02/25/2003					
	A151	6,555,839	04/29/2003	Fitzgerald				
	A152	6,573,126	06/03/2003	Cheng et a	ıl.			
	A153	6,583,015	06/24/2003	Fitzgerald	et al.			
	A154	6,593,191	07/15/2003	Fitzgerald	·····			
	A155	6,593,641	07/15/2003	Fitzgerald				
<u></u>	A156	6,602,613	08/05/2003	Fitzgerald				
	A157	6,603,156	08/05/2003	Rim				
	A158	6,646,322	11/11/2003	Fitzgerald				
	A159	6,649,480	11/18/2003	Fitzgerald	et al.			
	A160	6,677,192	01/13/2004	Fitzgerald			 	
	A161	6,703,144	03/09/2004	Fitzgerald				03/18/2003

EXAMINER

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EXAM. INIT.		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	A162	6,703,688	03/09/2004	Fitzgerald			07/16/2001
	A163	6,709,903	03/23/2004	Christiansen			04/30/2003
<u></u>	A164	6,713,326	03/30/2004	Cheng et al.			03/04/2003
•	A165	6,723,661	04/20/2004	Fitzgerald			07/16/2001
	A166	6,724,008	04/20/2004	Fitzgerald			07/16/2001
	A167	6,730,551	05/04/2004	Lee et al.			08/02/2002
	A168	6,737,670	05/18/2004	Cheng et al.			03/07/2003
	A169	6,750,130	06/15/2004	Fitzgerald			01/07/2001

FOREIGN PATENT DOCUMENTS

EXAM .INIT.		DOCUMENT NUMBER	DATE	COUNTRY CODE	CLASS	SUB CLASS	FILING DATE	ABSTRACT ONLY	ENGLISH LANG (Y/N)
-	В1	41 01 167	07/23/1992	DE				N	Y (Abstract only)
	B2	0 514 018	11/19/1992	EP				N	Y
	ВЗ	0 587 520	03/16/1994	EP				N	Y
	B4	0 683 522	11/22/1995	EP				N	Y
····	B5	0 828 296	03/11/1998	EP				N	Y
	В6	0 829 908	03/18/1998	EP				N	Y
	В7	0 838 858	04/29/1998	EP				N	Y (Abstract only)
·	В8	1 020 900	07/19/2000	EP			ï	N	Y
	В9	1 174 928	01/23/2002	EP				N	Y
	B10	2 701 599	09/01/1993	FR				Y	Y
	B11	2 342 777	04/19/2000	GB				N	Y
	B12	61/141116	06/28/1986	JP				N	Y (Abstract only)
	B13	2/210816	08/22/1990	ĴР				N	Y (Abstract only)
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FORM	PTO	- 1449		_			ATTY DOCKET NO.: ASC-049C1					· · · · · · · · · · · · · · · · · · ·
INFOR	MAT	TION DISCLO	SUR	E STAT	EM	ENT	APPLIC	ANT: Fitz	gerald			
							SERIAL	NO.: 10/7	774,890			
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					U.	S. PATEN	T DOCU	MENTS				
EXAM. INIT.		DOCUMEN' NUMBER	Г	DATE		NAME			CLASS	SUB CLASS		LING DATE IF PPROPRIATE
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				F	ORI	EIGN PAT	ENT DO	CUMENT	S			
EXAM . INIT.		DOCUMENT NUMBER	DA'	re	CO CO	UNTRY DE	CLASS	SUB CLASS	FILING DATE	ABSTRAC ONLY	T	ENGLISH LANG (Y/N)
	B14	3/036717	02/	18/1991	JP					N		Y
	B15	4-307974	10/	30/1992	JP	•				N		Y (Abstract only)
	B16	5-166724	07/	23/1993	JP					N		Y (Abstract only)
	B17	6-177046	06/	24/1994	JP	-				N		Y (Abstract only)
	B18	6-244112	09/	02/1994	JP					Y		Y
	B19	6-252046	09/	09/1994	JP					Y		Y
·	B20	7-094420	04/	07/1995	JP					N		Y (Abstract only)
	B21	7-106446	04/	21/1995	JP	·				Y		Y
	B22	7-240372	09/	12/1995	JP					Y		Y
	B23	10-270685		09/1998	JP					N		Y
	B24	11-233744	08/	27/1999	JP					N		Y (Abstract only)
	B25			21/2000	JP					N		Y
	B26	2000-031491		28/2000	JP					Y		Y
	B27	2001-319935		16/2001	JP					N		Y
	B28			15/2002	JP					N		Y
	B29		<u> </u>	07/2002	JP					N		Y
	B30	2002-289533		04/2002	JP					N		Y
	B31	98/59365	L	30/1998	WC					N		Y
	B32			21/1999	WC					N		Y
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	B36	01/54202	07/26/2001	WO				N		Y
	B37	01/93338	12/06/2001	WO				N		Y
	B38	01/99169	12/27/2001	WO				N		Y
	B39	02/13262	02/14/2002	WO				N		Y
	B40	02/15244	02/21/2002	WO				N		Y
	B41	02/27783	04/04/2002	WO				N		Y
	B42	02/47168	06/13/2002	WO				N		Y
	B43	02/071488	09/12/2002	wo				N		Y
	B44	02/071491	09/12/2002	wo				N		Y
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